SECTION II

LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<table>
<tr><td>MANUFACTURER
NAME & ADDRESS

TTM Technologies, Inc.
Stafford Division
4 Old Monson Road, P.O. Box 145
Stafford, CT 06075</td><td>PLANT LOCATION

Same</td><td>CAGE CODE: 5L706

CONTACT: Michele Herbert
PHONE #: (860) 684-5881
FAX #: (860) 684-7425
EMAIL: michele.hebert@ttmtech.com</td></tr>
<tr><td colspan="2">CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:</td><td>QUALIFICATION LETTER:</td></tr>
<tr><td colspan="2">MIL-PRF-31032/1
MIL-PRF-31032/2

Panel Size: 30” X 54”
Max. Board Thickness: 1.088”
Max./Min,.Hole Size: 0.09510”/0.221” drilled
Aspect Ratio: 10:1
Buried Via Aspect Ratio: 1:1
Max. Number of Layers: 68
Min. Conductor Width: 0.004”
Min. Conductor Spacing: 0.004”
Part Mounting: SMT, THM, MIX, Press Fit
Base Material: AF (Woven Aramid, Epoxy Resin)
BF (Nonwoven, Aramid Fabric, EpoxyResin)
BI (Nonwoven Aramid Reinforced Polyimide Resin)
GF (Woven E-glass, Epoxy resin)
GI (Woven E-glass, Polyimide resin)
GM (Woven E-Glass, Triazine/Bismaleimide Modified Epoxy Resin)
SC (Woven S-glass Cyanate Ester)
Finish System: HASL, SMOBC, Reflowed Solder, Electroless Nickel/Immersion Gold, Electrolytic Hard and Soft Gold, Electrolytic Nickel, Bright Tin, Immersion Tin
Hole Preparation: Plasma Etchback
Copper Plating: Electroless and Electrolytic Copper
Solder Resist: LPI, Dry Film, Wet Mask, Hole Fill, Hole Plug
Controlled Impedance: Range 30-150 ohms (± 10%), Microstrip, Embedded Microstrip, Dual Stripline, Characteristic, Differential
Alternate Construction: Copper Invar Copper, Blind and Buried Vias, Micro Vias, Buried Resistors, Multiple Laminations</td><td>VQE-03-3348</td></tr>
</table>

SECTION II

LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER NAME & ADDRESS	PLANT LOCATION	CAGE CODE: 5L706
TTM Technologies, Inc. Stafford Division 4 Old Monson Road, P.O. Box 145 Stafford, CT 06075	Same	CONTACT: Michele Herbert PHONE #: (860) 684-5881 FAX #: (860) 684-7425 EMAIL: michele.hebert@ttmtech.com
CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:		QUALIFICATION LETTER:
MIL-PRF-31032/3 MIL-PRF-31032/4		VQE-03-3349
Panel Size	30" X 54"	
Max. Board Thickness	0.300"/0.003"	
Max./Min,.Hole Size	0.221"/0.0095" drilled	
Aspect Ratio	9:1	
Buried Via Aspect Ratio	5:1	
Max. Number of Layers	28	
Min. Conductor Width	0.004"	
Min. Conductor Spacing	0.004"	
Part Mounting	SMT, THM, MIX GF (Woven E-glass, Epoxy resin) GI (Woven E-glass, Polyimide resin)	
Flex Base Material	IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless SC (Woven S-glass Cyanate Ester)	
Finish System	HASL, SMOBC, Reflowed Solder, Electroless Nickel/Immersion Gold, Electrolytic Hard and Soft Gold, Electrolytic Nickel, Bright Tin, Immersion Tin	
Hole Preparation	Plasma Etchback	
Copper Plating	Electroless and Electrolytic Copper	
Solder Resist	LPI, Dry Film, Wet Mask, Hole Fill, Hole Plug	
Controlled Impedance Embedded	Range 30-150 ohms (± 10%), Microstrip, Microstrip, Dual Stripline, Characteristic, Differential	
Alternate Construction	Copper Invar Copper, Blind and Buried Vias, Micro Vias, Buried Resistors, Multiple Laminations	
Flexibility Class	Class A (Flex During Installation) Class B (Continuous Flexing)	